

ABSTRACT

5 A process for manufacturing a composite polymeric circuit protection device in which
a polymeric assembly is provided and is then subdivided into individual devices. The
assembly is made by providing first and second laminates, each of which includes a laminar
polymer element having at least one conductive surface, providing a pattern on at least one of
the conductive surfaces on one laminate, securing the laminates in a stack in a desired
configuration, at least one conductive surface of at least one of the laminates forming an
10 external conductive surface of the stack, and making a plurality of electrical connections
between a conductive surface of the first laminate and a conductive surface of the second
laminate. The laminar polymer elements may be PTC conductive polymer compositions, so
that the individual devices made by the process exhibit PTC behavior.

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